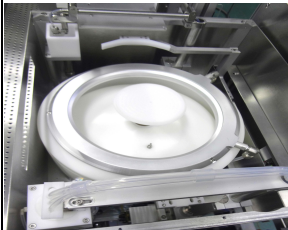

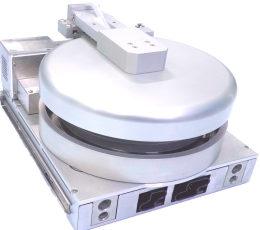

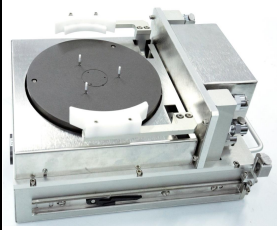


## PCT-150CRS TRACK SYSTEM

(R&D or Lab WITH SINGLE TRACK (1 COATER, 1 DEVELOPER) TOOL SETS

Please contact Sales [sales@picotrack.com](mailto:sales@picotrack.com) for more information



Coater Module	Developer Module	VPO Module	HPO Module	CP Module
				

Track System Specification	Description																	
System designed	US Standard System																	
System Configuration  (*Configuration available upon request)	<table border="1"> <tr> <td rowspan="4">DEV</td> <td>VPO</td> <td>HPO</td> </tr> <tr> <td>HPO</td> <td>HPO</td> </tr> <tr> <td>CP</td> <td>CP</td> </tr> <tr> <td>CP-CENT</td> <td>CP-CENT</td> </tr> <tr> <td colspan="3">SHUTTLE ARM</td> </tr> <tr> <td rowspan="2">COAT</td> <td>SEND</td> <td>SEND</td> </tr> <tr> <td>REC</td> <td>REC</td> </tr> </table>	DEV	VPO	HPO	HPO	HPO	CP	CP	CP-CENT	CP-CENT	SHUTTLE ARM			COAT	SEND	SEND	REC	REC
DEV	VPO		HPO															
	HPO		HPO															
	CP		CP															
	CP-CENT	CP-CENT																
SHUTTLE ARM																		
COAT	SEND	SEND																
	REC	REC																
System dimension	Length: 47" ; Width: 47" ; Height: 90"																	
Wafer size (workable dual size)	Up to 6" (150mm) or 4" & 6" auto conversion																	
Wafer shape	Round/Square/Rectangular/Triangle/Special																	
Wafer material	Silicon/Sapphire/GaAs/ Ceramic...																	
Wafer sensor	Optical sensor mapping																	
System controller	PC & PLC Controller with Windows OS based																	
Chemical canister cabinet	Solvent (EBR, HMDS, Cleaning...), developer liquid																	
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles																	
Indexer wafer cassettes capacity	2 or 4 (available upon request)																	
Shuttle Robot Arm	1 Robot arm and dual end effectors																	
System Fan Filter Unit (FFU)	optional																	
System SECs/GEM	optional																	
<b>Coater</b>	<b>1 module</b>																	
Catch Cup Set	Up/down motion																	
Spindle Unit	Fixed position																	
Maximum spin speed	7000 rpm																	
Spin motor type	Servo																	
Spin speed accuracy	± 3 rpm																	
Acceleration range	0-50000 rpm/sec																	
Dispense arm accuracy	± 0.1 mm																	
Wafer centering	± 0.1 mm																	
Dispense arm motion control	Stepper motor drive and rotation																	
Dispense arm # 1 & nozzles	3x or more (3/16" or 1/4" OD) (Standard)																	
Dispense arm # 2 & nozzles	3x or more (3/16" or 1/4" OD) (Optional)																	
Dispense method	Static, and radial																	
Pre-dispense function	Yes																	
Top/Bottom EBR	Yes																	
Catch-cup rinse(CCR)	Optional																	
Cleaning tip nozzle	Optional																	
Humidity & Temperature control	Optional																	
Photoresist temperature control	Optional (≤ 1°C; 10-50°C range)																	
*Spray Coater module is available	Optional																	
<b>Developer</b>	<b>1 module</b>																	
Catch Cup Set	Up/down motion																	
Spindle Unit	Fixed position																	
Maximum spin speed	7000 rpm																	
Spin motor type	Servo																	
Spin speed accuracy	± 3 rpm																	

Acceleration range	0-50000 rpm/sec
Spin direction	Clockwise (+) & counter clockwise (-)
Dispense arm motion control	Stepper motor drive and rotation
Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm # 1 nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Standard)
Dispense arm # 2 nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Option)
Negative developer nozzles	Cone or fan spray with N2 air assist (Upon request)
Developer dispense type	Stream, Puddle, Fan spray, Cone spray....
Dispense method	Static, radial and sweep
DI water top and back side rinse	Yes
N2 Airing back side	Yes
N2 Blow-off top nozzle	Optional
Developer liquid Temp. controller	Optional (≤ 1°C; 10-50°C range)
<b>Vapor Prime Ovent (VPO)</b>	<b>1 module (Stack up)</b>
VPO block type	Aluminum anodized with vacuum slots
VPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	Up to 200°C, Δt: 50°C ≤ 200s
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-200°C)
HMDS prime method	Fume shower on top by pressurized N2 with bubbler
Wafer carrier	3 pins controlled by stepper motor
Wafer contact angle	≥ 65° on prime silicon wafer
Contact angle uniformity	≤ 1.5° on prime base silicon wafer
Bake method	Contact, vacuum & purge bake
<b>Hot Plate Oven (HPO)</b>	<b>3 modules (Stack up)</b>
HPO block type	Aluminum anodized with vacuum slots or proximity
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	25-250°C, Δt: 50°C ≤ 200s (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
<b>Chill Plate &amp; Centering (CP-CENT)</b>	<b>4 modules (Stack up)</b>
Chill Plate block type	Aluminum anodized with vacuum slots or proximity
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Chill method	Contact or proximity
Cooling Water Temperature controller	Optional
Wafer carrier	3 pins controlled by stepper motor, and or air cylinder
Wafer Centering	Integrated